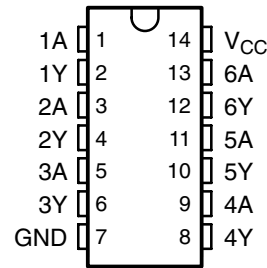


CD74ACT05-Q1 HEX INVERTER WITH OPEN-DRAIN OUTPUTS

SCHS350A – JANUARY 2004 – REVISED JANUARY 2008

- Qualified for Automotive Applications
- Inputs Are TTL-Voltage Compatible
- Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption
- Balanced Propagation Delays
- ± 24 -mA Output Drive Current
 - Fanout to 15 F Devices
- SCR-Latchup-Resistant CMOS Process and Circuit Design

M PACKAGE
(TOP VIEW)



description

The CD74ACT05 contains six independent inverters. This device performs the Boolean function $Y = \bar{A}$. The open-drain outputs require pullup resistors to perform correctly, and can be connected to other open-drain outputs to implement active-low wired-OR or active-high wired-AND functions.

ORDERING INFORMATION†

| T _A | PACKAGE‡ | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|----------------|----------|---------------|-----------------------|------------------|
| –40°C to 125°C | SOIC – M | Tape and reel | CD74ACT05QM96Q1 | ACT05Q |

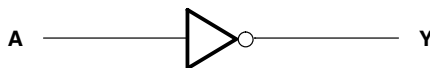
† For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at <http://www.ti.com>.

‡ Package drawings, thermal data, and symbolization are available at <http://www.ti.com/packaging>.

FUNCTION TABLE
(each inverter)

| INPUT A | OUTPUT Y |
|------------|-------------|
| H | L |
| L | Z |

logic diagram, each inverter (positive logic)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

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CD74ACT05-Q1 HEX INVERTER WITH OPEN-DRAIN OUTPUTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

| | |
|---|----------------|
| Supply voltage range, V_{CC} | –0.5 V to 6 V |
| Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1) | ±20 mA |
| Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1) | ±50 mA |
| Continuous output current, I_O ($V_O = 0$ to V_{CC}) | ±50 mA |
| Continuous current through V_{CC} or GND | ±100 mA |
| Package thermal impedance, θ_{JA} (see Note 2) | 86°C/W |
| Storage temperature range, T_{stg} | –65°C to 150°C |

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

| | $T_A = 25^\circ\text{C}$ | | –40°C TO 125°C | | UNIT |
|--|--------------------------|----------|----------------|----------|------|
| | MIN | MAX | MIN | MAX | |
| V_{CC} Supply voltage | 4.5 | 5.5 | 4.5 | 5.5 | V |
| V_{IH} High-level input voltage | 2 | | 2 | | V |
| V_{IL} Low-level input voltage | | 0.8 | | 0.8 | V |
| V_I Input voltage | 0 | V_{CC} | 0 | V_{CC} | V |
| V_O Output voltage | 0 | 5.5 | 0 | 5.5 | V |
| I_{OH} High-level output current | | –24 | | –24 | mA |
| I_{OL} Low-level output current | | 24 | | 24 | mA |
| $\Delta t/\Delta v$ Input transition rise or fall rate | | 10 | | 10 | ns/V |

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | V_{CC} | $T_A = 25^\circ\text{C}$ | | –40°C TO 125°C | | UNIT |
|-----------------|----------------------------------|-----------------------------------|--------------------------|------|----------------|------|------|
| | | | MIN | MAX | MIN | MAX | |
| V_{OL} | $V_I = V_{IH}$ or V_{IL} | $I_{OL} = 50 \mu\text{A}$ | 4.5 V | 0.1 | | 0.1 | V |
| | | $I_{OL} = 24 \text{ mA}$ | 4.5 V | 0.36 | | 0.5 | |
| | | $I_{OL} = 50 \text{ mA}^\ddagger$ | 5.5 V | | | 1.65 | |
| I_I | $V_I = V_{CC}$ or GND | 5.5 V | | ±0.1 | | ±1 | μA |
| I_{CC} | $V_I = V_{CC}$ or GND, $I_O = 0$ | 5.5 V | | 4 | | 80 | μA |
| ΔI_{CC} | $V_I = V_{CC} - 2.1 \text{ V}$ | 4.5 V to 5.5 V | | 2.4 | | 3 | mA |
| C_i | | | | 10 | | 10 | pF |

[‡] Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 75-Ω transmission-line drive capability at 125°C.



ACT INPUT LOAD TABLE

| INPUT | UNIT LOAD |
|-------|-----------|
| A | 0.18 |

Unit load is ΔI_{CC} limit specified in electrical characteristics table (e.g., 2.4 mA at 25°C).

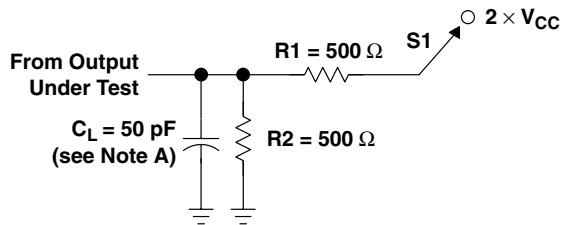
switching characteristics over recommended operating free-air temperature range, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | -40°C TO 125°C | | UNIT |
|-----------|--------------|-------------|----------------|------|------|
| | | | MIN | MAX | |
| t_{PZL} | A or B | Y | 2.3 | 9.3 | ns |
| t_{PLZ} | | | 2.7 | 10.8 | |

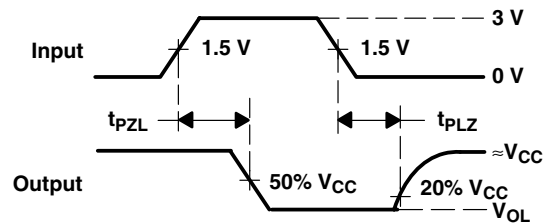
operating characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

| PARAMETER | TYP | UNIT |
|--|-----|------|
| C_{pd} Power dissipation capacitance | 105 | pF |

PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT



**VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES**

- NOTES: A. C_L includes probe and jig capacitance.
 B. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 3\text{ ns}$, $t_f \leq 3\text{ ns}$.
 C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|-------------------|---------------|--------------|-----------------|------|-------------|-------------------------|------------------|----------------------|--------------|-------------------------|-------------------------|
| CD74ACT05QM96G4Q1 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | ACT05Q | Samples |
| CD74ACT05QM96Q1 | ACTIVE | SOIC | D | 14 | | TBD | Call TI | Call TI | -40 to 125 | ACT05Q | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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OTHER QUALIFIED VERSIONS OF CD74ACT05-Q1 :

- Catalog: [CD74ACT05](#)
- Military: [CD54ACT05](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4040047-5/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AB.

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